



PRELIMINARY DATA SHEET

BIPOLAR ANALOG INTEGRATED CIRCUIT μ PC2710TB

5 V, SUPER MINIMOLD SILICON MMIC MEDIUM OUTPUT POWER AMPLIFIER

DESCRIPTION

The μ PC2710TB is a silicon monolithic integrated circuits designed as PA driver for 900 MHz band cellular telephone tuners. This IC is packaged in super minimold package which is smaller than conventional minimold.

The μ PC2710TB has compatible pin connections and performance to μ PC2710T of conventional minimold version. So, in the case of reducing your system size, μ PC2710TB is suitable to replace from μ PC2710T.

This IC is manufactured using NEC's 20 GHz fr NESAT™ III silicon bipolar process. This process uses silicon nitride passivation film and gold electrodes. These materials can protect chip surface from external pollution and prevent corrosion/migration. Thus, this IC has excellent performance, uniformity and reliability.

FEATURES

- High-density surface mounting : 6-pin super minimold package
- Supply voltage : $V_{CC} = 4.5$ to 5.5 V
- Wideband response : $f_u = 1.0$ GHz TYP. @ 3 dB bandwidth
- Medium output power : $P_{O(sat)} = +13.5$ dBm TYP. @ $f = 500$ MHz with external inductor
- Power gain : $G_P = 33$ dB TYP. @ $f = 500$ MHz
- Port impedance : input/output 50Ω

APPLICATION

- PA driver for 900 MHz band cellular telephone

ORDERING INFORMATION

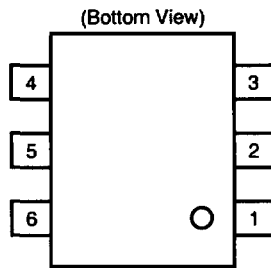
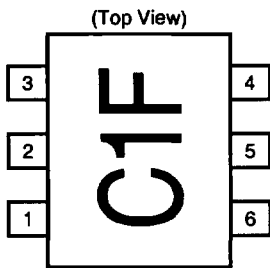
Part Number	Package	Marking	Supplying Form
μ PC2710TB-E3	6-pin super minimold	C1F	Embossed tape 8 mm wide. 1, 2, 3 pins face to perforation side of the tape. Qty 3 kp/reel

Remark To order evaluation samples, please contact your local NEC sales office. (Part number for sample order: μ PC2710TB)

Caution Electro-static sensitive devices

The information in this document is subject to change without notice.

PIN CONNECTIONS



Pin No.	Pin Name
1	INPUT
2	GND
3	GND
4	OUTPUT
5	GND
6	V _{CC}

PRODUCT LINE-UP OF μ PC2710 (T_A = +25°C, V_{CC} = V_{out} = 5.0 V, Z_L = Z_S = 50 Ω)

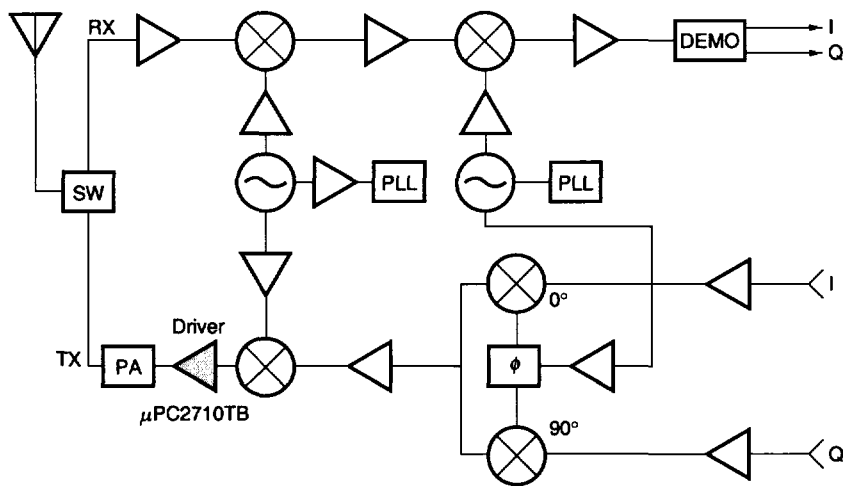
Part No.	f _u (GHz)	P _{O(sat)} (dBm)	G _p (dB)	NF (dB)	I _{cc} (mA)	Package	Marking
μ PC2710T	1.0	+13.5	33	3.5	22	6-pin minimold	C1F
μ PC2710TB						6-pin super minimold	

Remark Typical performance. Please refer to **ELECTRICAL CHARACTERISTICS** in detail.

Notice The package size distinguishes between minimold and super minimold.

SYSTEM APPLICATION EXAMPLE

EXAMPLE OF 900 MHz BAND DIGITAL CELLULAR TELEPHONE



PIN EXPLANATION

Pin No.	Pin Name	Applied Voltage V	Pin Voltage V ^{Note}	Function and Applications	Internal Equivalent Circuit
1	INPUT	–	0.90	Signal input pin. A internal matching circuit, configured with resistors, enables 50 Ω connection over a wide band. A multi-feedback circuit is designed to cancel the deviations of h _{FE} and resistance. This pin must be coupled to signal source with capacitor for DC cut.	
4	OUTPUT	Voltage as same as V _{cc} through external inductor	–	Signal output pin. The inductor must be attached between V _{cc} and output pins to supply current to the internal output transistors.	
6	V _{cc}	4.5 to 5.5	–	Power supply pin, which biases the internal input transistor. This pin should be externally equipped with bypass capacitor to minimize its impedance.	
2 3 5	GND	0	–	Ground pin. This pin should be connected to system ground with minimum inductance. Ground pattern on the board should be formed as wide as possible. All the ground pins must be connected together with wide ground pattern to decrease impedance difference.	

Note Pin voltage is measured at V_{cc} = 5.0 V

ABSOLUTE MAXIMUM RATINGS

Parameter	Symbol	Conditions	Ratings	Unit
Supply Voltage	V _{CC}	T _A = +25°C, Pin 4 and 6	5.8	V
Total Circuit Current	I _{CC}	T _A = +25°C	60	mA
Power Dissipation	P _D	Mounted on double copper clad 50 × 50 × 1.6 mm epoxy glass PWB (T _A = +85°C)	200	mW
Operating Ambient Temperature	T _A		-40 to +85	°C
Storage Temperature	T _{stg}		-55 to +150	°C
Input Power	P _{in}	T _A = +25°C	+10	dBm

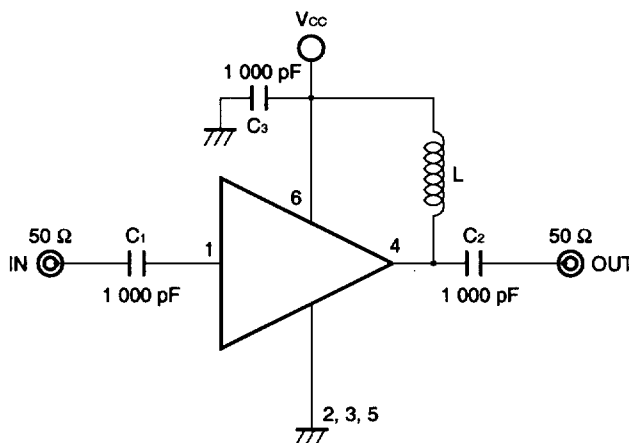
RECOMMENDED OPERATING CONDITIONS

Parameter	Symbol	MIN.	TYP.	MAX.	Unit	Notice
Supply Voltage	V _{CC}	4.5	5.0	5.5	V	The same voltage should be applied to pin 4 and 6.
Operating Ambient Temperature	T _A	-40	+25	+85	°C	

ELECTRICAL CHARACTERISTICS (T_A = +25°C, V_{CC} = V_{out} = 5.0 V, Z_s = Z_L = 50 Ω)

Parameter	Symbol	Test Conditions	MIN.	TYP.	MAX.	Unit
Circuit Current	I _{CC}	No Signal	16	22	29	mA
Power Gain	G _P	f = 500 MHz	30	33	36.5	dB
Maximum Output Level	P _{O(sat)}	f = 500 MHz, P _{in} = -8 dBm	+11	+13.5	-	dBm
Noise Figure	NF	f = 500 MHz	-	3.5	5.0	dB
Upper Limit Operating Frequency	f _u	3 dB down below flat gain at f = 0.1 GHz	0.7	1.0	-	GHz
Isolation	ISL	f = 500 MHz	34	39	-	dB
Input Return Loss	RL _{in}	f = 500 MHz	3	6	-	dB
Output Return Loss	RL _{out}	f = 500 MHz	9	12	-	dB
Gain Flatness	ΔG _P	f = 0.1 to 0.6 GHz	-	±0.8	-	dB

TEST CIRCUIT



COMPONENTS OF TEST CIRCUIT FOR MEASURING ELECTRICAL CHARACTERISTICS

	Type	Value
C ₃	Capacitor	1 000 pF
L	Bias Tee	1 000 nH
C ₁ to C ₂	Bias Tee	1 000 pF

EXAMPLE OF ACTURAL APPLICATION COMPONENTS

	Type	Value	Operating Frequency
C ₁ to C ₃	Chip Capacitor	1 000 pF	100 MHz or higher
L	Chip Inductor	300 nH	10 MHz or higher
		100 nH	100 MHz or higher
		10 nH	1.0 GHz or higher

INDUCTOR FOR THE OUTPUT PIN

The internal output transistor of this IC consumes 20 mA, to output medium power. To supply current for output transistor, connect an inductor between the Vcc pin (pin 6) and output pin (pin 4). Select large value inductance, as listed above.

The inductor has both DC and AC effects. In terms of DC, the inductor biases the output transistor with minimum voltage drop to output enable high level. In terms of AC, the inductor make output-port impedance higher to get enough gain. In this case, large inductance and Q is suitable.

CAPACITORS FOR THE Vcc, INPUT AND OUTPUT PINS

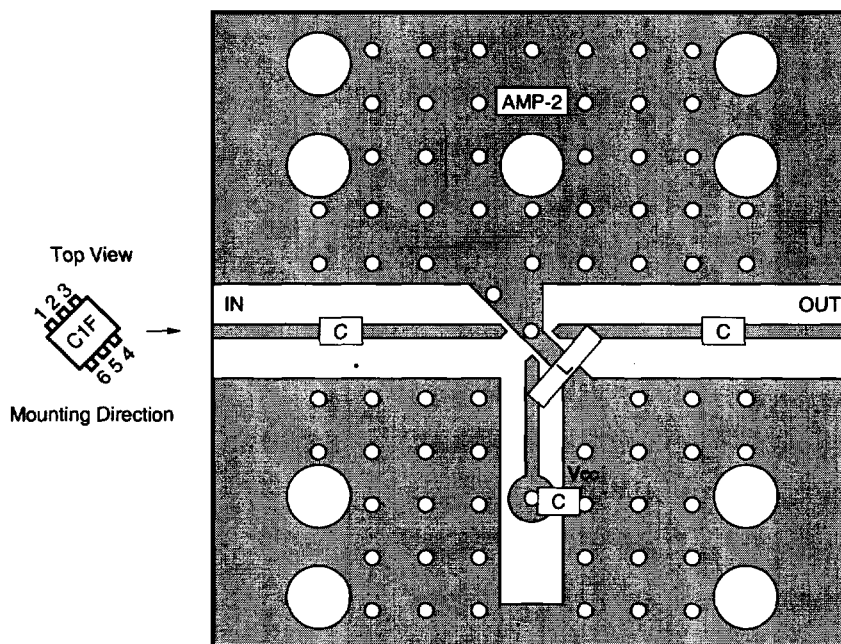
Capacitors of 1000 pF are recommendable as the bypass capacitor for the Vcc pin and the coupling capacitors for the input and output pins.

The bypass capacitor connected to the Vcc pin is used to minimize ground impedance of Vcc pin. So, stable bias can be supplied against Vcc fluctuation.

The coupling capacitors, connected to the input and output pins, are used to cut the DC and minimize RF serial impedance. Their capacitance are therefore selected as lower impedance against a 50 Ω load. The capacitors thus perform as high pass filters, suppressing low frequencies to DC.

To obtain a flat gain from 100 MHz upwards, 1000 pF capacitors are used in the test circuit. In the case of under 10 MHz operation, increase the value of coupling capacitor such as 10000 pF. Because the coupling capacitors are determined by equation, $C = 1/(2 \pi R f c)$.

ILLUSTRATION OF THE TEST CIRCUIT ASSEMBLED ON EVALUATION BOARD



COMPONENT LIST

	Value
C	1 000 pF
L	300 nH

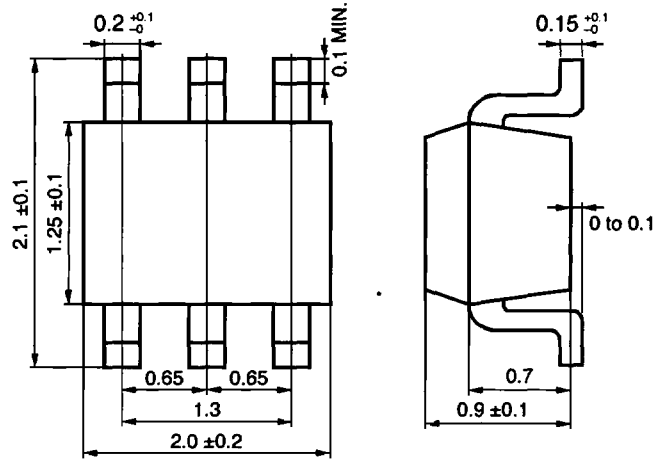
Notes

1. 30 × 30 × 0.4 mm double sided copper clad polyimide board.
2. Back side: GND pattern
3. Solder plated on pattern
4. ○ ○ : Through holes

For more information on the use of this IC, refer to the following application note: USAGE AND APPLICATION OF SILICON MEDIUM-POWER HIGH-FREQUENCY AMPLIFIER MMIC (P12152E).

PACAGE DIMENSIONS

6 pin super minimold (Unit: mm)



NOTES ON CORRECT USE

- (1) Observe precautions for handling because of electro-static sensitive devices.
- (2) Form a ground pattern as wide as possible to minimize ground impedance (to prevent undesired oscillation).
All the ground pins must be connected together with wide ground pattern to decrease impedance difference.
- (3) The bypass capacitor should be attached to Vcc line.
- (4) The inductor must be attached between Vcc and output pins. The inductance value should be determined in accordance with desired frequency.
- (5) The DC cut capacitor must be attached to input pin.

This product should be soldered in the following recommended conditions. Other soldering methods and conditions than the recommended conditions are to be consulted with our sales representatives.

Soldering Method	Soldering Conditions	Recommended Condition Symbol
Infrared Ray Reflow	Package peak temperature: 235°C Hour: within 30 s. (more than 210°C) Time: 3 times, Limited days: no ^{Note}	IR35-00-3
VPS	Package peak temperature: 215°C Hour: within 40 s. (more than 200°C) Time: 3 times, Limited days: no ^{Note}	VP15-00-3
Wave Soldering	Soldering tub temperature: less than 260°C, Hour: within 10 s. Time: 1 times, Limited days: no ^{Note}	WS60-00-1
Pin Part Heating	Pin area temperature: 300°C, Hour: within 3 s/pin. Limited days: no ^{Note}	

Note It is the storage days after opening a dry pack, the storage conditions are 25°C, less than 65% RH.

Caution The combined use of soldering method is to be avoided (However, except the pin area heating method).

For details of recommended soldering conditions for surface mounting, refer to information document SEMICONDUCTOR DEVICE MOUNTING TECHNOLOGY MANUAL (C10535E).

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**ATTENTION**

OBSERVE PRECAUTIONS
FOR HANDLING
ELECTROSTATIC
SENSITIVE
DEVICES

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Anti-radioactive design is not implemented in this product.